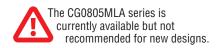


Features

RoHS compliant*

- ESD protection >25 kV
- Surge protection
- Low capacitance

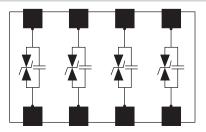


ChipGuard® CG0805MLA Series - ESD Protector Array

General Information

The ChipGuard® CG0805MLA series has been designed to provide a competitive solution for applications where capacitance of the ESD protector is less critical. General ESD applications in end products such as computers, analog modems and PDAs include IC supply lines, MOSFET gate protection, and low frequency digital and control lines.

The ChipGuard® CG0805MLA guad device is designed to protect equipment to IEC61000-4-2, Level 4 (±8 kV Contact / ±15 kV Air Discharge) ESD specification.



Electrical & Thermal Characteristics @ TA = 25 °C (unless otherwise noted)

Parameter	Symbol	CG0805MLA-5.5ME	CG0805MLA-18KE	Unit
Maximum AC Working Voltage @ 10 μ A Max.	V _{RMS}	4	14	V
Maximum DC Working Voltage @ 10 μ A Max.	V _{DC}	5.5	18	V
Minimum Resistance @ 3.3 VDC	IR	10		Megohms
Maximum Peak Current @ 8/20 μ S Pulse	IS	10	5	А
Maximum Transient Energy @ 10/1000 µS Pulse	W _{Max}	0.01		Joules
Nominal Breakdown Voltage @ 1 mA	V _{BR}	12	28	V
Breakdown Voltage Tolerance	%_ V _{BR}	20	10	%
Maximum Clamping Voltage @ 1 A 8/20 μ S Pulse	VC	28	58	V
Typical Capacitance @ 1 VRMS 1 kHz	C _{O1}	36	17	pF
Typical Capacitance @ 1 VRMS 1 MHz	C _{O2}	33	15	pF
Maximum Response Time	RT	1		ns
ESD Protection: Per IEC 61000-4-2 Min. Contact Discharge (>100 Reps) Min. Air Discharge (>100 Reps)		±8 ±15		kV kV
Operating Temperature	T _{OPR}	-40 to +85		°C
Storage Temperature	TSTG	-40 to +85		°C



*RoHS Directive 2015/863. Mar 31. 2015 and Annex.

Specifications are subject to change without notice. Users should verify actual device performance in their specific applications.

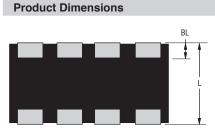
The products described herein and this document are subject to specific legal disclaimers as set forth on the last page of this document, and at www.bourns.com/docs/legal/disclaimer.pdf.

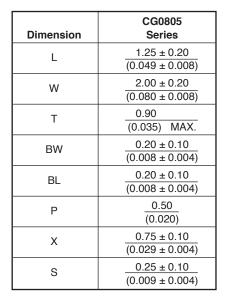
Applications

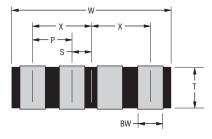
- IC supply line protection
- MOSFET gate protection
- Control line protection
- Low frequency I/O line protection

ChipGuard® CG0805MLA Series - ESD Protector Array

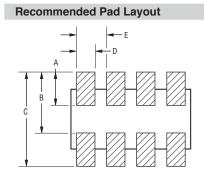
BOURNS





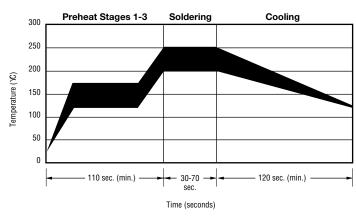


DIMENSIONS: MM (INCHES)



Dimension	CG0805 Series
А	<u>0.64</u> (0.025)
В	<u>1.27</u> (0.050)
С	<u>1.91</u> (0.075)
D	<u>0.28</u> (0.011)
E	<u>0.51</u> (0.020)

Solder Reflow Recommendations



A	Stage 1 Preheat	Ambient to Preheating Temperature	30 s to 60 s
В	Stage 2 Preheat	140 °C to 160 °C	60 s to 120 s
С	Stage 3 Preheat	Preheat to 200 °C	20 s to 40 s
D	Main Heating	200 °C 210 °C 220 °C 230 °C 240 °C	60 s to 70 s 55 s to 65 s 50 s to 60 s 40 s to 50 s 30 s to 40 s
Е	Cooling	200 °C to 100 °C	1 °C/s to 4 °C/s

This product can be damaged by rapid heating, cooling or localized heating.

Heat shocks should be avoided. Preheating and gradual cooling recommended.

· Excessive solder can damage the device. Print solder thickness of 150 to 200 um recommended.

• Solder gun tip temperature should be kept below 280 °C and should not touch the device directly. Contact should be less than 3 seconds.

A solder gun under 30 watts is recommended.

Specifications are subject to change without notice.

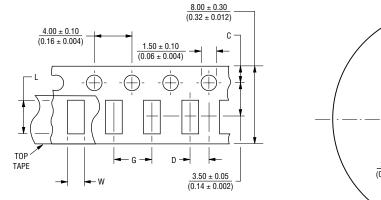
Users should verify actual device performance in their specific applications.

The products described herein and this document are subject to specific legal disclaimers as set forth on the last page of this document, and at www.bourns.com/docs/legal/disclaimer.pdf.

ChipGuard® CG0805MLA Series - ESD Protector Array

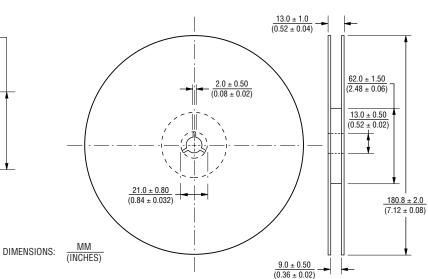
BOURNS

Packaging Dimensions

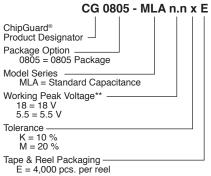


NOTES: TAPE MATERIAL IS PAPER. TAPE THICKNESS IS $\frac{0.60 \pm 0.05}{(0.024 \pm 0.002)}$ COVER TAPE ADHESION IS 40 ± 15 GRAMS.

Dimension	CG0805 Series
С	$\frac{1.75 \pm 0.10}{(0.069 \pm 0.004)}$
D	$\frac{2.00 \pm 0.05}{(0.080 \pm 0.002)}$
L	$\frac{2.40 \pm 0.20}{(0.094 \pm 0.008)}$
W	$\frac{1.65 \pm 0.20}{(0.065 \pm 0.008)}$
G	$\frac{4.00 \pm 0.10}{(0.16 \pm 0.004)}$



How to Order



** Only models lower than 10 volts require decimal point.

Specifications are subject to change without notice. Users should verify actual device performance in their specific applications. The products described herein and this document are subject to specific legal disclaimers as set forth on the last page of this document, and at <u>www.bourns.com/docs/legal/disclaimer.pdf</u>.